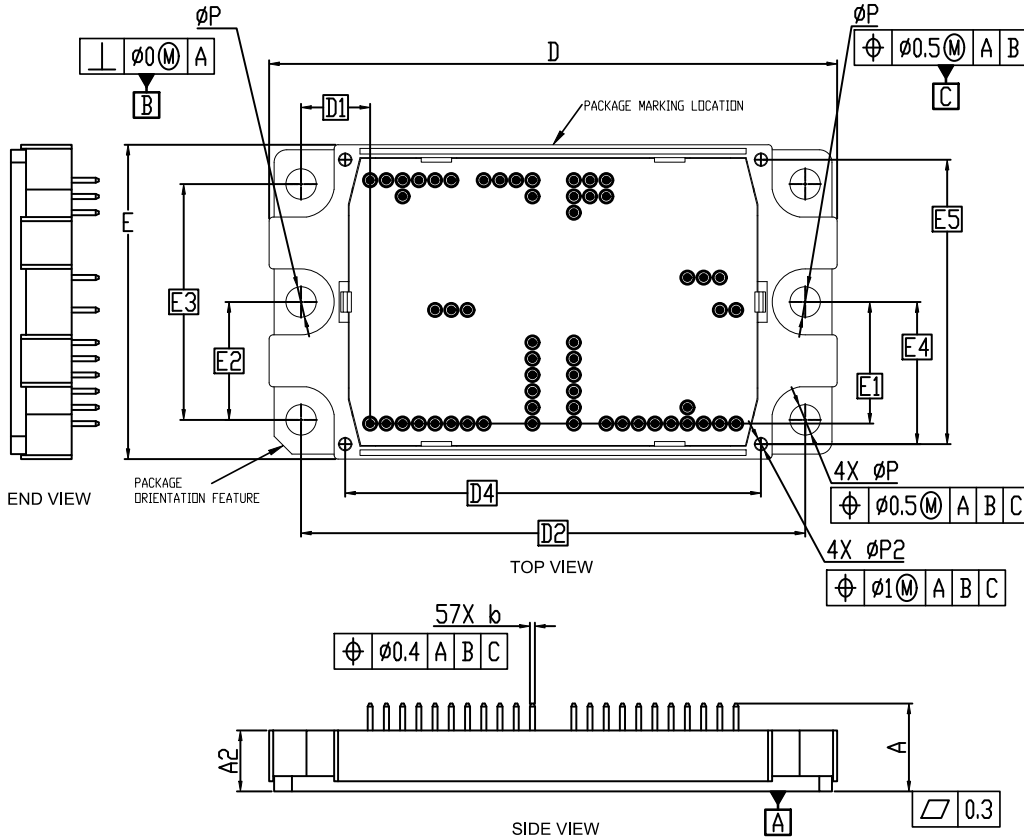


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NOTES:

1. Dimensioning and tolerancing conform to ASME Y14.5
2. All dimensions are in millimeters.
3. Pin-grid is 3.2mm.
4. Package marking is located on the side opposite the package orientation feature.
5. The pins are gold-plated solder pin.



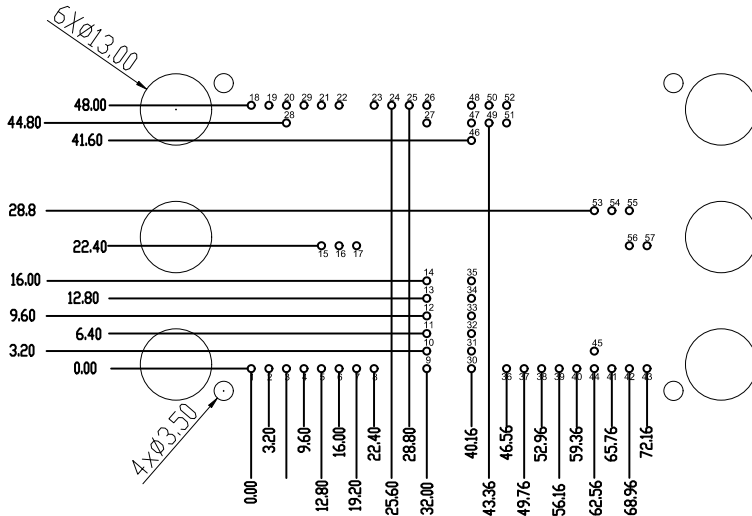
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	17.00	17.40	17.80
A2	11.70	12.00	12.30
b	0.95	1.00	1.05
D	111.60	112.00	112.40
D1	13.62 BSC		
D2	99.40 BSC		
D4	82.00 BSC		
E	61.60	62.00	62.40
E1	24.00 BSC		
E2	23.25 BSC		
E3	46.50 BSC		
E4	28.05 BSC		
E5	56.10 BSC		
P	5.90	6.00	6.10
P2	2.20	2.30	2.40

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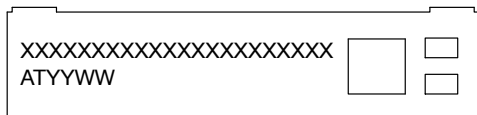
RECOMMENDED
MOUNTING PATTERN

* For additional information on our Pb-Free strategy and soldering details, please download the Onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

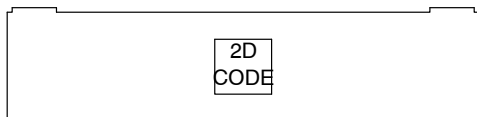
NOTE 2:

Pin table								
Pin	X	Y	Pin	X	Y	Pin	X	Y
1	0	0	23	22.4	48	45	62.56	3.2
2	3.2	0	24	25.6	48	46	40.16	41.6
3	6.4	0	25	28.8	48	47	40.16	44.8
4	9.6	0	26	32	48	48	40.16	48
5	12.8	0	27	32	44.8	49	43.36	44.8
6	16	0	28	6.4	44.8	50	43.36	48
7	19.2	0	29	9.6	48	51	46.56	44.8
8	22.4	0	30	40.16	0	52	46.56	48
9	32	0	31	40.16	3.2	53	62.56	28.8
10	32	3.2	32	40.16	6.4	54	65.76	28.8
11	32	6.4	33	40.16	9.6	55	68.96	28.8
12	32	9.6	34	40.16	12.8	56	68.96	22.4
13	32	12.8	35	40.16	16	57	72.16	22.4
14	32	16	36	46.56	0			
15	12.8	22.4	37	49.76	0			
16	16	22.4	38	52.96	0			
17	19.2	22.4	39	56.16	0			
18	0	48	40	59.36	0			
19	3.2	48	41	65.76	0			
20	6.4	48	42	68.96	0			
21	12.8	48	43	72.16	0			
22	16	48	44	62.56	0			

GENERIC
MARKING DIAGRAM*



FRONTSIDE MARKING



BACKSIDE MARKING

XXXXX = Specific Device Code
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "µ", may or may not be present. Some products may not follow the Generic Marking.

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